

Applicable standard					
Rating	Operating temperature range	-40 °C to +105°C (Note1)	Storage temperature range	-10 °C to +60°C (Note3)	
	Operating humidity range	20% to 80% (Note2)	Storage humidity range	40% to 70% (Note3)	
	Applicable connector	DF61Y-2S-2.2C	Current	AWG 28 : 3.0A	
	Voltage	350 V AC/DC		AWG 26 : 3.2A AWG 24 : 4.0A	
Specifications					
Item		Test method	Requirements	QT	AT
Construction					
General examination		Visually and by measuring instrument.	According to drawing.	X	X
Marking		Confirmed visually.		X	X
Electric characteristics					
Contact resistance millivolt level method		20mV MAX, 1mA (DC or 1000Hz).	10 mΩ MAX.	X	—
Insulation resistance		500 V DC.	1000 MΩ MIN.	X	—
Voltage proof		1200 V AC for 1 MIN.	No flashover or breakdown.	X	—
Mechanical characteristics					
Mechanical operation		30 times insertion and extraction.	①Contact resistance: 20 mΩ MAX. ②No damage, crack or looseness of parts.	X	—
Contact insertion and extraction forces		It takes out and inserts with a conformity connector.	①Insertion force : 20.0N MAX. ②Extraction force: 0.5N MIN.	X	—
Vibration		Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 10 cycles for 3 direction.	①No electrical discontinuity of 1 μ s. ②No damage, crack or looseness of parts.	X	—
Shock		490 m/s <sup>2</sup> duration of pulse 11 ms at 3 times for 3 directions.		X	—
Environmental characteristics					
Damp heat (Steady state)		Exposed at 40 ± 2°C , 90 to 95 %, 96 h. (after leaving the room temperature for 1-2h.)	①Contact resistance: 20 mΩ MAX. ②Insulation resistance: 500 MΩ MIN. ③No damage, crack or looseness of parts.	X	—
Rapid change of temperature		Temperature -55°C→ +85°C Time 30MIN→ 30MIN Under 5 cycles. (The transferring time of the tank is 2-3 MIN) (After leaving the room temperature for 1-2h.)	①Contact resistance: 20 mΩ MAX. ②Insulation resistance: 500 MΩ MIN. ③No damage, crack or looseness of parts.	X	—
Resistance to soldering heat		1) Reflow soldering « Reflow time » Number of reflow cycles : 2 cycles MAX. Duration above 220 °C, 60 sec. MAX. Peak temperature: 250°C 10 sec. MAX. « Pre-heat time » Pre-heat temperature(MIN) :150 °C Pre-heat temperature(MAX) :180 °C Pre-heat time(MIN) : 90 sec. Pre-heat time(MAX) : 120 sec. 2) Manual soldering Soldering iron temperature :350±10°C, Soldering time : 3sec. No strength on contact.	No deformation of case of excessive looseness of the terminals.	X	—
Solderability		Soldering temperature : 245°C Duration of immersion :soldering, for 5 sec.	New uniform coating of solder shall cover minimum of 95 % of the surface being immersed.	X	—
Remarks					
Note 1: Include the temperature rising by current.					
Note 2: No condensing					
Note 3:Apply to the condition of long term storage for unused products befor pcb on board, After pcb on board, operating temperature and humiditty range is applied for interim storage during transportation.					
	Count	Description of revisions	Designed	Checked	Date
①	1				
Unless otherwise specifid , refer to IEC 60512.			Approved	KI. AKIYAMA	15.06.11
			Checked	HK. UMEHARA	15.06.11
			Designed	ST. SATO	15.06.11
			Drawn	MI. SAKIMURA	15.06.11
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			Drawing no.		ELC-361873-23-00
<b>HRS</b>	Specification sheet		Part no.	DF61Y-2P-2. 2V (23)	
	Hirose electric co., ltd.		Code no.	CL666-5100-3-23	① 1/1